

Investor Fact Sheet

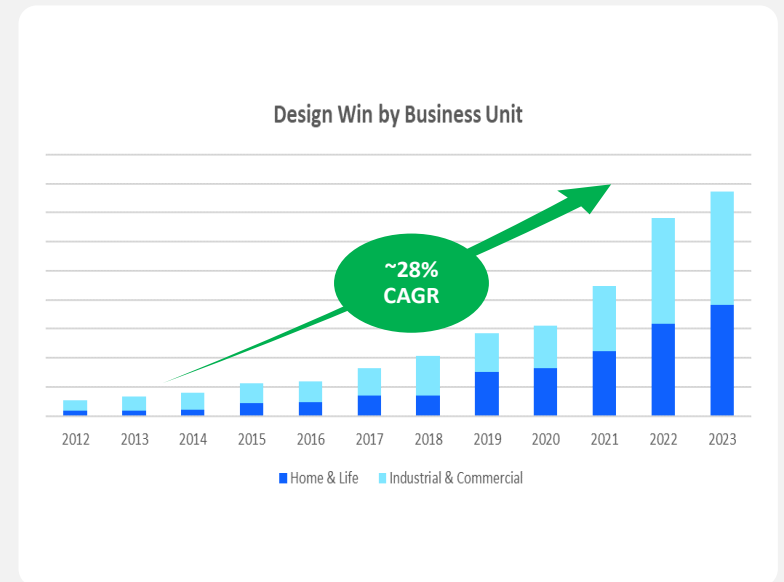
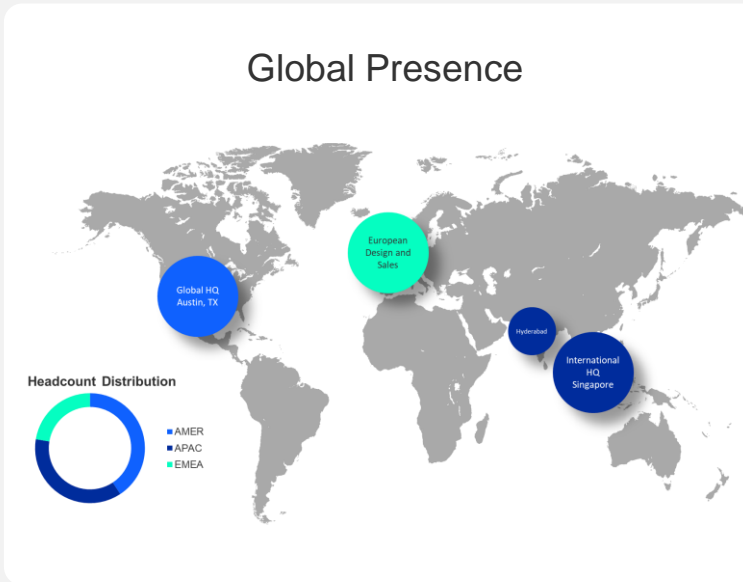
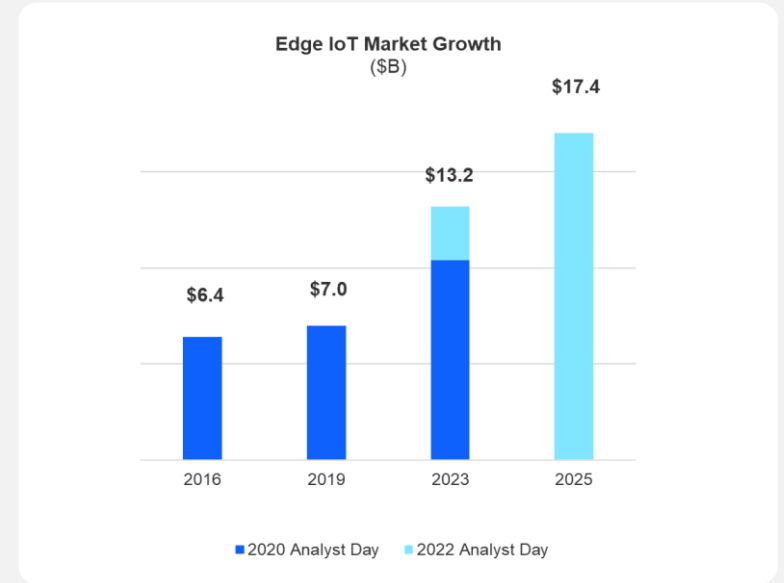
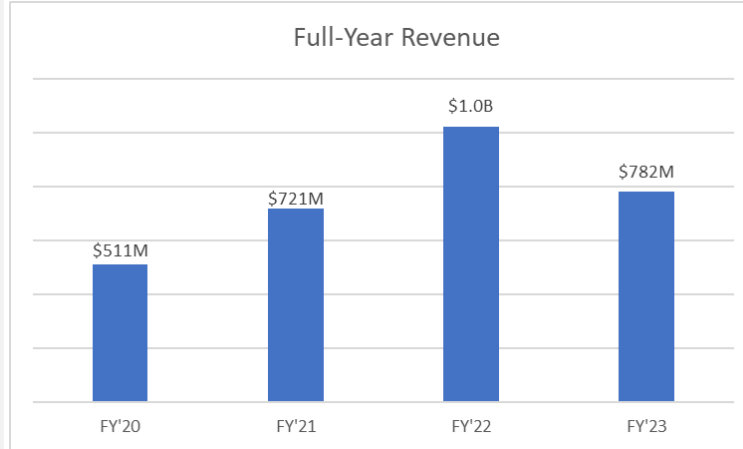
All information is current as of 2/07/2024 unless otherwise noted

Silicon Labs (NASDAQ: SLAB) is a leader in secure, intelligent wireless technology for a more connected world.

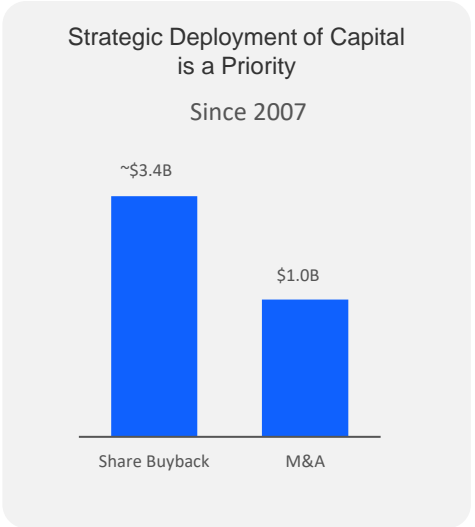
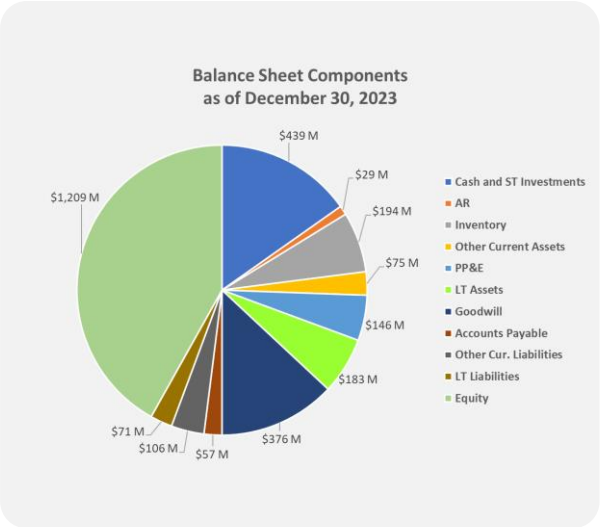
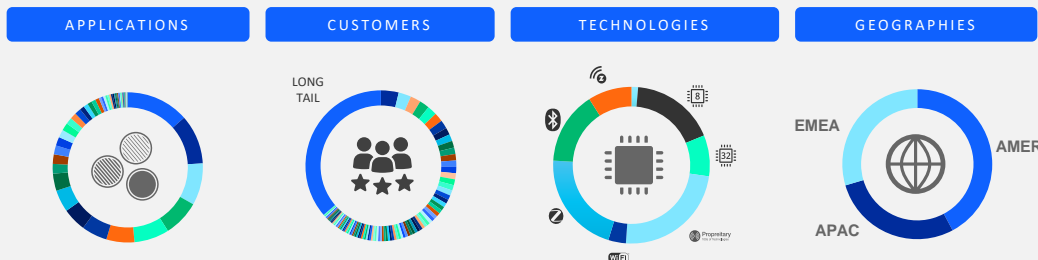
-  Focus on large & growing markets
-  Robust breadth and depth of protocols & ecosystems
-  Strong & sustainable growth, highly attractive target model
-  Channel revenue ~80% of total revenue

Headquartered in Austin, Texas, with ~2,000 employees, creating a global perspective that is an integral part of our culture.

For complete information regarding Silicon Labs' financial results, please visit <https://investor.silabs.com>



Integrated hardware and software platform – supporting more wireless protocols than anyone in the industry – for industrial, commercial, home and life applications, reaching tens of thousands of global customers



Recent Business Highlights

In Q1 2023, Silicon Labs announced a new integrated circuit family designed for the smallest form factor IoT devices: the xG27 family of Bluetooth SoCs. The xG27 family offers IoT device designers the energy efficiency, high performance, security, and wireless connectivity ideal for tiny, battery-optimized devices like connected medical devices, wearables, asset monitoring tags, and smart sensors.

Silicon Labs announced the availability of its Pro Kit for Amazon Sidewalk, which has been developed to simplify the development process, reduce costs, and accelerate time to revenue for Amazon Sidewalk devices. As one of Amazon Sidewalk's only three qualified hardware partners for developing Amazon Sidewalk devices, our Pro Kit provides all the necessary tools for developing high-volume, scalable IoT applications.

Announced the new dual-band FG28 SoC, designed for long-range networks and protocols like Amazon Sidewalk, Wi-SUN, and other proprietary protocols. The FG28 includes radios for sub-Gigahertz (Ghz) and 2.4 Ghz Bluetooth LE, making it particularly attractive for edge applications in growth areas like smart agriculture, smart cities, and neighborhood networks. The built-in AI/ML accelerator is a first for a sub-Ghz SoC, bringing AI/ML to the edge.

In Q3 2023, Silicon Labs hosted its fourth annual Works With Conference in August, which attracted thousands of top IoT developers, and included panels with partners from Amazon, Google, Samsung, and many more.

In Q4 2023, Silicon Labs was selected as an honoree in the Embedded Technologies category at the CES 2024 Innovation Awards for its SiWx917 SoC. The x917 is the first Wi-Fi 6 combo chip in the Silicon Labs portfolio and is a Matter-ready, fully integrated single-chip solution with industry-leading low power consumption, ideal for secure cloud connectivity.

Announced the first phase of its collaboration with Arduino to integrate the Matter protocol into Arduino's integrated development environment, bringing simplicity and ease of use to wireless development for Silicon Labs developers as well as Arduino's 40 million users. Silicon Labs continues to lead in contributing to Matter development and mass market adoption.

Announced general availability for our flagship FG25 sub-Ghz SoC. The FG25 is ideal for long-range, low-power communications, capable of broadcasting more than 1km with minimal data loss in dense, urban environments. With Wi-SUN certification, the FG25 also supports high data bandwidth of up to 3.6 Megabits per second, which is critical for enabling the large networks needed by smart cities.

In Q2 2023, Silicon Labs held the grand opening of the Silicon Labs Connectivity Lab in our Boston site, an event attended by top customers and partners. The Connectivity Lab simulates a modern Smart Home, with a range of IoT devices, applications, ecosystems, and networks. It offers developers an ideal environment to test their Matter prototypes.

Finalized the previously announced redemption process on its 2025 convertible notes. The company funded the \$535 million par value of the notes in cash. The in-the-money component of the converted notes was settled with the issuance of approximately 0.9 million shares.

Announced its next-generation Series 3 platform, purpose-built for embedded IoT devices. Series 3 devices will be designed to offer industry-leading compute, wireless performance, scalability, and energy efficiency with the highest levels of IoT security. New levels of compute will bring more than 100X the processing capability of Series 2 and will include integrated AI/ML accelerators for edge devices, enabling consolidation of system processing into wireless SoCs.

On January 25th, 2024, the company's board of directors authorized a \$100 million repurchase plan for the company's common stock valid through the end of 2024.